TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (Ultra-High-Speed U-MOSIII)

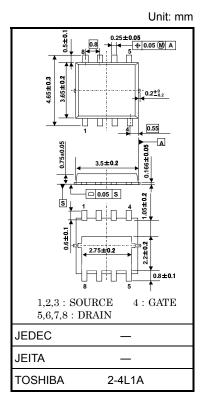
# **TPCM8001-H**

High-Efficiency DC / DC Converter Applications
Notebook PC Applications
Portable-Equipment Applications

- · Small footprint due to a small and thin package
- High-speed switching
- Small gate charge: QSW = 6.0 nC (typ.)
- Low drain-source ON-resistance:  $RDS(ON) = 7 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance:  $|Y_{fs}| = 36 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$
- Enhancement mode:  $V_{th} = 1.1 \text{ to } 2.3 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

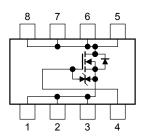
### Absolute Maximum Ratings (Ta = 25°C)

Characte	eristic	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	30	V	
Drain-gate voltage (R	$k_{GS} = 20 \text{ k}\Omega$ )	$V_{DGR}$	30	V	
Gate-source voltage		$V_{GSS}$	±20	V	
Drain current	DC (Note 1)	ΙD	20	А	
Diam curicit	Pulsed (Note 1)	I <sub>DP</sub>	60		
Drain power dissipati	on (Tc=25°C)	$P_{D}$	30	W	
Drain power dissipation	on $(t = 10 s)$ (Note 2a)	$P_{D}$	2.3	W	
Drain power dissipation	on (t = 10 s) (Note 2b)	$P_{D}$	1.0	W	
Single-pulse avalance	he energy (Note 3)	E <sub>AS</sub>	104	mJ	
Avalanche current		I <sub>AR</sub>	20	Α	
Repetitive avalanche	energy c=25°C) (Note 4)	E <sub>AR</sub>	1.8	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	-55 to 150	°C	



Weight: 0.028 g (typ.)

### **Circuit Configuration**



Note: For Notes 1 to 4, refer to the next page.

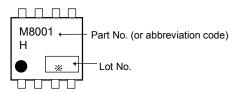
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

### **Thermal Characteristics**

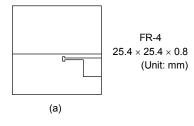
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25°C)	R <sub>th (ch-c)</sub>	4.17	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	54.3	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

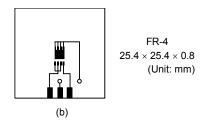
### Marking (Note 5)



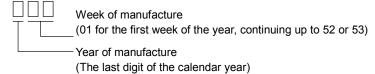
- Note 1: The channel temperature should not exceed 150°C during use.
- Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





- Note 3:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (initial), L = 0.2 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 20 A
- Note 4: Repetitive rating: pulse width limited by max channel temperature
- Note 5: on the lower left of the marking indicates Pin 1.
  - \* Weekly code: (Three digits)



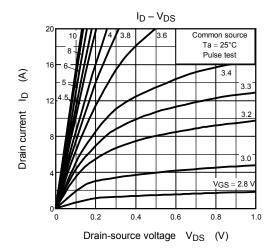
## Electrical Characteristics (Ta = 25°C)

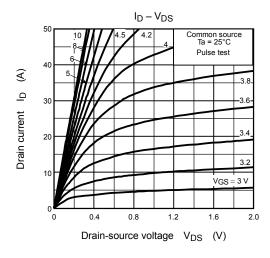
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$		_	±10	μА	
Drain cutoff curre	ent	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	10	μΑ	
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	30	_	_	V	
Diaiii-source bre	akuowii voitage	V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15 — —		l v		
Gate threshold ve	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.1	_	2.3	V	
Drain agurag ON	raciatanas	Dec (cv)	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	_	10	14		
Drain-source ON-resistance		R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A	_	7	9.5	mΩ	
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 A	18	36	_	S	
Input capacitance	e	C <sub>iss</sub>		_	1130	_		
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	120	_	pF	
Output capacitance		C <sub>oss</sub>			480	_		
Switching time	Rise time	t <sub>r</sub>	Vgs 10 V	_	2.5	_	ns ns	
	Turn-on time	t <sub>on</sub>		_	9	_		
	Fall time	t <sub>f</sub>		_	3			
	Turn-off time	t <sub>off</sub>	$V_{DD} \simeq 15 \text{ V}$ Duty $\leq 1\%$ , $t_W = 10  \mu \text{s}$	_	19			
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	_	19	_		
			$V_{DD} \simeq 24~V,~V_{GS} = 5~V,~I_D = 20~A$		11	_		
Gate-source charge 1		Q <sub>gs1</sub>	$V_{DD} \simeq 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	_	3.9	_	nC	
Gate-drain ("Miller") charge		Q <sub>gd</sub>		_	4.0	_		
Gate switch charge		Q <sub>SW</sub>		_	6.0	_		

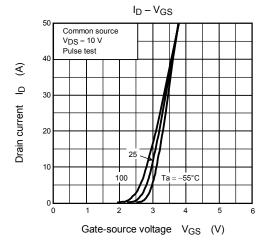
## Source-Drain Ratings and Characteristics (Ta = 25°C)

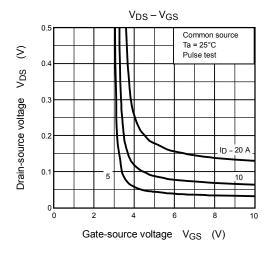
Character	istic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	_	_	_	60	Α
Forward voltage (diode)			V <sub>DSF</sub>	I <sub>DR</sub> = 20 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

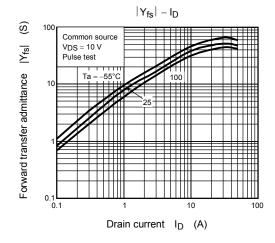
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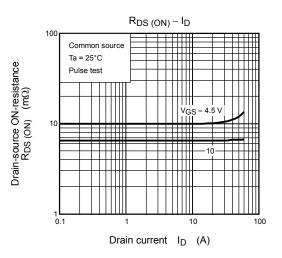




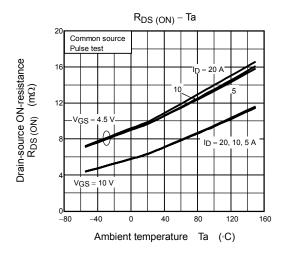


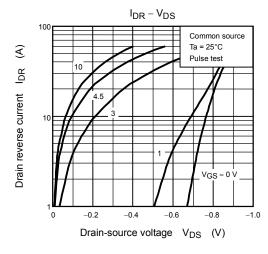


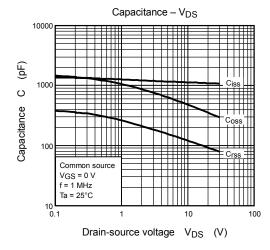


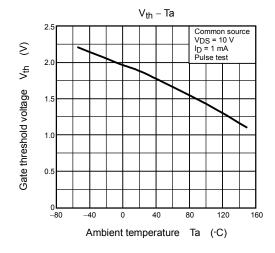


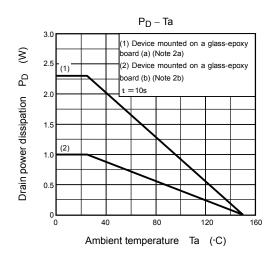
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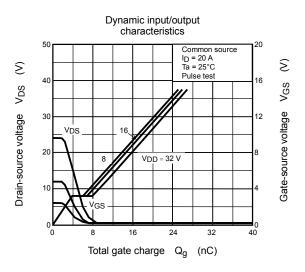


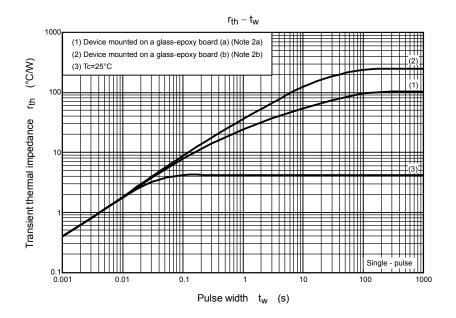


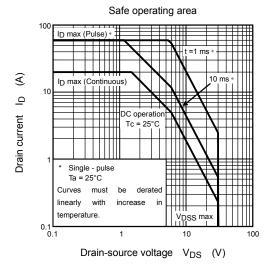


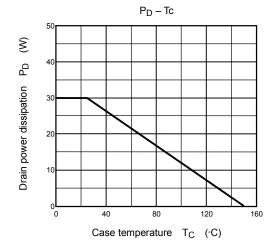












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